

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

38. (Currently amended) A semiconductor device, comprising:  
a substrate having contact pads exposed at a surface thereof, saidthe contact pads being arranged in at least one substantially linear relationship positioned at or proximate a centerline of saidthe substrate and being configured to communicate with corresponding test pads of a test substrate upon disposing saidthe substrate face-down over saidthe test substrate; and at least one stabilizer protruding from saidthe surface, saidthe at least one stabilizer being configured to at least partially stabilize an orientation of the semiconductor device upon disposal thereof face-down over saidthe test substrate and including a plurality of superimposed, contiguous, mutually adhered layers of the same material.

39. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer protrudes from saidthe surface at most a distance between a plane of saidthe surface of saidthe substrate and a plane of a surface of saidthe test substrate upon disposing saidthe substrate face-down over saidthe test substrate.

40. (Currently amended) The semiconductor device of claim 39, wherein saidthe at least one stabilizer protrudes from saidthe surface at most the distance between saidthe plane of saidthe surface of saidthe substrate and saidthe plane of saidthe surface of saidthe test substrate when at least one conductor connects at least one of saidthe contact pads and a corresponding one of saidthe test pads.

41. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer comprises a dielectric material.

42. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer comprises a photopolymer.

43. (Currently amended) The semiconductor device of claim 42, wherein saidthe photopolymer is at least semisolid.

44. (Canceled)

45. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer is positioned to be located proximate a corner of saidthe surface.

46. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer is positioned to be located proximate an edge of saidthe surface.

47. (Currently amended) The semiconductor device of claim 38, wherein saidthe at least one stabilizer has a cross-sectional plan of one of quadrilateral, round, oval, and triangular.

48. (Previously presented) The semiconductor device of claim 38, wherein saidthe at least one stabilizer is elongated in a direction parallel to a plane in which saidthe substrate is located.

49. (Currently amended) The semiconductor device of claim 38, wherein saidthe substrate comprises a semiconductor wafer.

50. (Currently amended) The semiconductor device of claim 38, wherein saidthe substrate comprises a semiconductor die.

51. (Currently amended) The semiconductor device of claim 38, wherein saidthe substrate comprises a chip-scale package.

52. (Currently amended) The semiconductor device of claim 38, wherein saidthe test substrate also includes at least one stabilizer configured to at least partially stabilize saidthe substrate upon disposing saidthe substrate face-down over saidthe test substrate.

53. (Currently amended) A test substrate, comprising:  
a substrate having test pads exposed at a surface thereof, saidthe test pads being arranged in at least one substantially linear relationship and configured to communicate with corresponding contact pads which are arranged in at least one substantially linear relationship which is positioned at or proximate a centerline of a semiconductor device to be disposed face-down over saidthe substrate; and  
at least one stabilizer protruding from saidthe surface, saidthe at least one stabilizer being configured to at least partially stabilize the semiconductor device upon disposal thereof face-down over the test substrate.

54. (Currently amended) The test substrate of claim 53, wherein saidthe at least one stabilizer protrudes from saidthe surface at most a distance between a plane of saidthe surface of saidthe substrate and a plane of a surface of saidthe semiconductor device upon disposing saidthe semiconductor device face-down over saidthe substrate.

55. (Currently amended) The test substrate of claim 54, wherein saidthe at least one stabilizer protrudes from saidthe surface at most the distance between saidthe plane of saidthe surface of saidthe substrate and saidthe plane of saidthe surface of saidthe semiconductor device when at least one conductor connects at least one of saidthe contact pads and a corresponding one of saidthe test pads.

56. (Currently amended) The test substrate of claim 53, wherein saidthe at least one stabilizer comprises a photopolymer.

57. (Currently amended) The test substrate of claim 56, wherein saidthe photopolymer is at least semisolid.

58. (Currently amended) The test substrate of claim 56, wherein saidthe at least one stabilizer comprises a plurality of superimposed, contiguous, mutually adhered layers.

59. (Currently amended) The test substrate of claim 53, wherein saidthe semiconductor device has at least one stabilizer secured to a surface thereof, saidthe at least one stabilizer configured to at least partially stabilize saidthe semiconductor device upon disposal of saidthe semiconductor device face-down over saidthe substrate.

60. (Currently amended) An assembly of a semiconductor device and a test substrate, comprising:

a test substrate with a plurality of test pads exposed at a surface thereof and arranged in at least one substantially linear relationship;

a semiconductor device with a plurality of contact pads exposed at a surface thereof, saidthe plurality of contact pads being arranged in at least one substantially linear relationship which is located at or proximate a centerline of saidthe semiconductor device, saidthe surface of saidthe semiconductor device facing saidthe surface of saidthe test substrate with saidthe plurality of contact pads in temporary communication with corresponding test pads of saidthe plurality of test pads; and

at least one stabilizer disposed between saidthe test substrate and saidthe semiconductor device.

61. (Currently amended) The assembly of claim 60, wherein saidthe at least one stabilizer is secured to saidthe surface of saidthe test substrate.

62. (Currently amended) The assembly of claim 60, wherein saidthe at least one stabilizer is secured to saidthe surface of saidthe semiconductor device.

63. (Currently amended) The assembly of claim 60, comprising a plurality of stabilizers, at least one of saidthe plurality of stabilizers being secured to saidthe surface of saidthe test substrate and at least one other of saidthe plurality of stabilizers being secured to saidthe surface of saidthe semiconductor device.

64. (Currently amended) The assembly of claim 60, wherein saidthe at least one stabilizer comprises a photopolymer.

65. (Currently amended) The assembly of claim 60, wherein saidthe photopolymer is at least semisolid.

66. (Currently amended) The assembly of claim 64, wherein saidthe at least one stabilizer has a plurality of superimposed, contiguous, mutually adhered layers.

67. (Currently amended) The assembly of claim 60, wherein saidthe at least one stabilizer extends between a plane of saidthe surface of saidthe test substrate and a plane of saidthe surface of saidthe semiconductor device at most a distance between saidthe planes of saidthe surfaces upon establishing communication between saidthe plurality of contact pads and saidthe corresponding test pads.

68. (Currently amended) The assembly of claim 60, further comprising at least one conductive structure disposed between saidthe test substrate and saidthe semiconductor device.

69. (Currently amended) The assembly of claim 68, wherein saidthe at least one stabilizer extends between a plane of saidthe surface of saidthe test substrate and a plane of saidthe surface of saidthe semiconductor device at most a distance saidthe at least one conductive structure extends between saidthe planes of saidthe surfaces.